

e2000/e2100 Qseven® GPU COMPUTE PRODUCTS – THE HETEROGENEOUS COMPUTING PLATFORM WITH SPACEFLIGHT HERITAGE



The e2000/e2100 heterogeneous computing product families are radiation tolerant high-performance compute modules for onboard data processing. The products have spaceflight heritage and use low power embedded x86 compatible AMD® G-series SOC products from the 1st, 2nd, and LX families. The SOC is paired with a powerful Microsemi® SmartFusion2™ FPGA which provides IO expansion and board supervisory management through IP core state-machines or embedded ARM® Cortex™ M3 micro-controller.

The e20xx/e21xx products provide common interfaces for command and data handling, robots, intelligent automation, and autonomous systems, including: Gigabit Ethernet, USB v2.0/v3.0, PCIe express®, SerDes, LVDS, SATA v3.0, Serial ports, GPIO, CAN 2.0b, I2C, and SPI. The GPIO capabilities of the FPGA can be used for optional interfaces using different (not included) IP cores.

UNIBAP® e20xx/e21xx families of products are the perfect choice for autonomous systems with high demands for data fusion and sensor interfaces using optimized heterogeneous parallel algorithms and extensive IO.

Reference: Bruhn, F.; Brunberg, K.; Hines, J.; Asplund, L.; Norgren, M., "Introducing radiation tolerant heterogeneous computers for small satellites," in Aerospace Conference, 2015 IEEE, vol., no., pp.1-10, 7-14

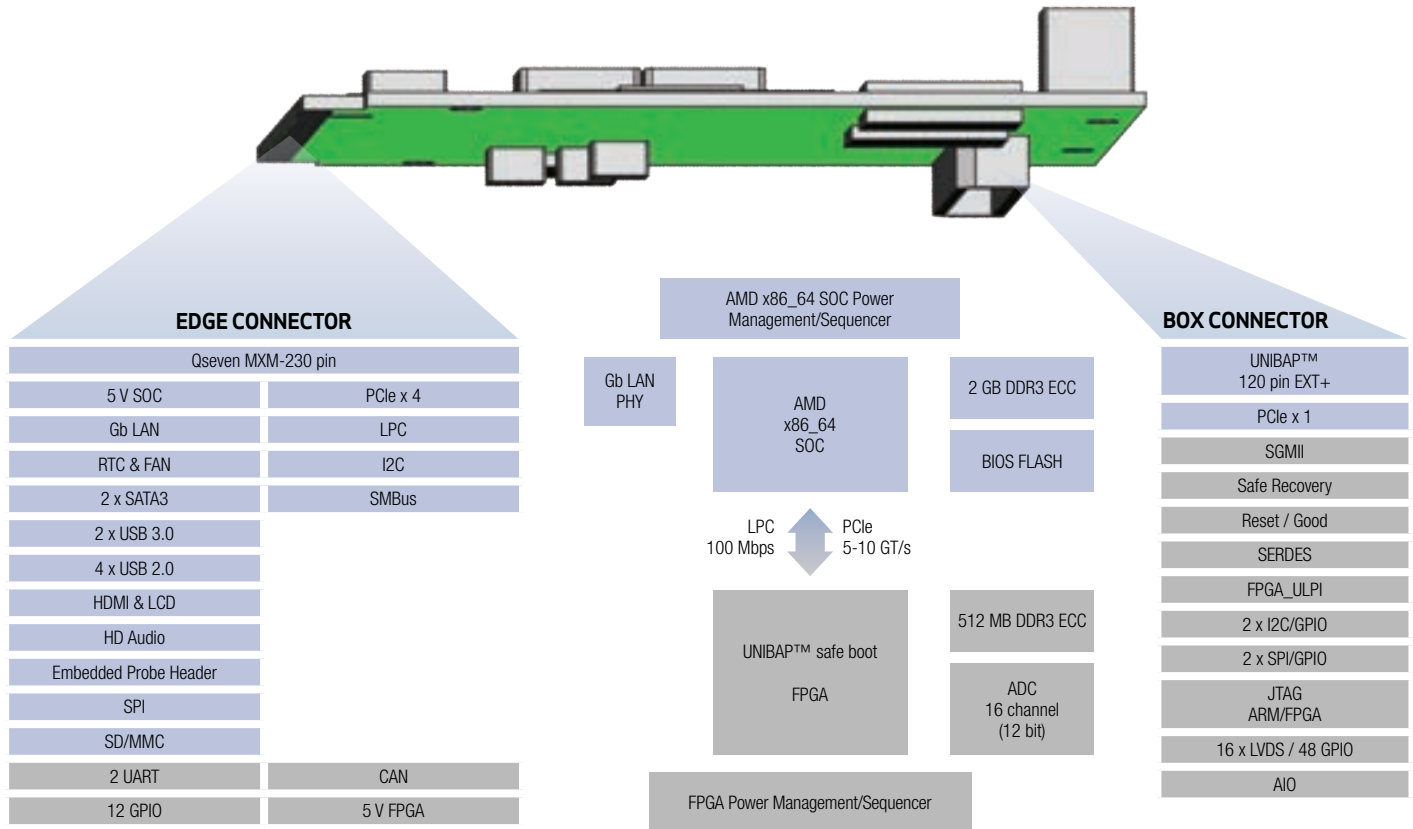
SPECIFICATIONS

Parameter	Description	Parameter	Description
AMD SoC CPU	AMD® Embedded G-series SOC Series 1st gen (e2000), 2nd gen (e2100), LX (e2190), 64 bit x86 Jaguar/Puma architecture.	FPGA Safety MCU	Microsemi® SmartFusion2™ ARM® Cortex™-M3 MCU
AMD SoC GPU	HD RADEON GPU, 2 CU (Up to 77 GFLOPS) DirectX™ 11.1, OpenCL™ 1.2, OpenCL 1.2+, OpenGL 4.5+, Vulcan 1.0, H.264 encoding/decoding	AMD OS	Linux (typ. LUbuntu) Opt. Windows 7, Solaris, VxWorks
Graphics Output	HDMI, LCD/LVDS (e2000), eDP (e21xx)	FPGA OS	Typ. Bare metal / FreeRTOS, Optional. RTEMS, Ada Ravenscar
Memory	SoC: 2 GB DDR3 1066 to 1333 with ECC FPGA: 512 MB DDR3 up to 667 with ECC	USB / SATA	2xUSB 3.0, 4xUSB 2.0, 2x SATA v3
Board size	70 × 70 mm ²	Interconnect	PCIe x4, 20 GT/s, PCIe 2x1 Lanes, 5 GT/s, PCIe x2 10 GT/s (AMD/FPGA)
Connectors/IO	Qseven® MXM 230, Unibap Ext Connector 120 IO	Ethernet	1 x 1000Base-T Gigabit (AMD), SGMII Interface (FPGA)
Temp. range	0 °C to 70 °C (Commercial) -40 °C to 70 °C (Ext. temperature, special)	Other	Serial/UART, CAN, I2C, SPI, GPIO, LVDS, SERDES.
Power reference	Depending on SoC selection and operational modes: 4-20 W. Typ. 10 W.	Qualification	IPC 6012C Class 2/3 PCB, IPC 610 Class 2/3 soldering, ECSS-Q-30 std derated components

Information may change at any time

e2000/e2100 QSEVEN® COMPUTE PRODUCTS HETEROGENEOUS COMPUTING PLATFORM WITH SPACEFLIGHT HERITAGE

e20XX AND e21XX FAMILY OF HETEROGENEOUS COMPUTATIONAL MODULES



e2000/e21000 FAMILY OPTIMIZED DEVELOPMENT ENVIRONMENT (ODE KIT)



ADVANCED HEALTH MONITORING AND REMOTE MAINTENANCE

- Voltages
- Currents
- Power consumption
- Temperatures
- Bit error detection and correction
- SoC power optimization

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